COMPACT FLOOR®

Wärmeleitschichten · Conductive Layers

CompactFloor® LIQUID

Installation



First adhere the floor heating across the entire subsurface using Mapei tile adhesive Ultralite S1 (2.5kg /m²) (24-h drying period).



Mix a canister of Latex Plus and a bag of Planitex D10 (~ 11 m²) using a slow-running mixer (max. 400 rpm).



Subsequently, pour the mixture onto the dust-free and clean heating elements.



Gradually create an even contact layer of 1 - 2 mm using a smooth trowel.



Allow to dry at 20 °C room temperature for at least six hours – cooler temperatures (min. 10° C) extend the drying period.



For the load-bearing layer, mix one bag of Planitex D10 with 6.5 I water and add one bag of fibres (250 g).



Add the load-bearing layer manually or using a screed pump and seamlessly distribute onto the completely dry contact layer.



Draw off the fluid load-bearing layer to 9 mm using a pin leveller.



At the earliest after a four-day drying period, perform the heating protocol CompactFloor LIQUID. Subsequently, after the control of the residual moisture, the floor covering can be laid.